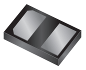
Package Details

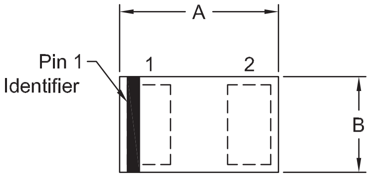
SOD-882 Case

Top View

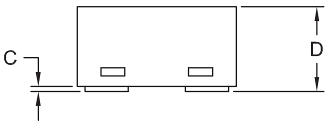


Bottom View

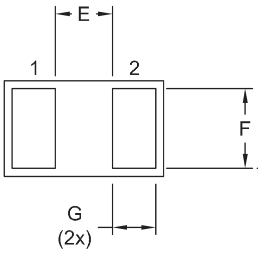
Mechanical Drawing



TOP VIEW



SIDE VIEW



BOTTOM VIEW R2

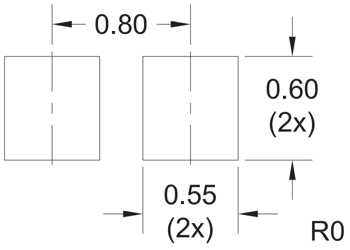
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.037	0.042	0.95	1.05
B	0.022	0.026	0.55	0.65
C	0.000	0.002	0.00	0.05
D	0.017	0.022	0.45	0.55
E	0.014		0.36	
F	0.017	0.022	0.45	0.55
G	0.008	0.013	0.22	0.32

SOD-882 (REV:R2)

Lead Code:
1) Cathode
2) Anode

Part Marking: One Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



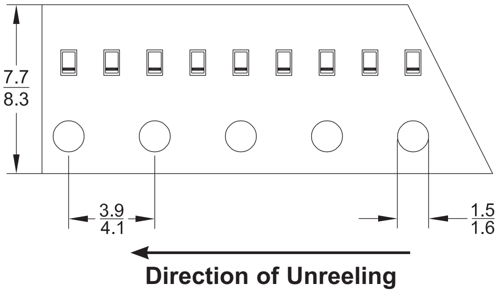
R0 (10-September 2014)

Package Details

SOD-882 Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

7” Reel = 8,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

Ordering Information

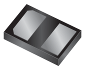
- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R0 (10-September 2014)

Material Composition Specification

SOD-882 Case


Top View


Bottom View

Device average mass . . . . **1.1 mg**
Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.64%	0.018	Si	7440-21-3	1.64%	0.018	16,364
bond wire	gold	0.36%	0.004	Au	7440-57-5	0.36%	0.004	3,636
leadframe	Cu alloy	21.31%	0.2344	Cu	7440-50-8	21.18%	0.233	211,818
				Cr	7440-47-3	0.05%	0.0005	455
				Sn	7440-31-5	0.05%	0.0005	455
				Zn	7440-66-6	0.04%	0.0004	364
die attach	silver epoxy	0.27%	0.003	Ag	7440-22-4	0.18%	0.002	1,818
				epoxy resin	Proprietary	0.09%	0.001	909
encapsulation*	EMC GREEN	75.24%	0.8276	silica (fused)	60676-86-0	58.27%	0.641	582,727
				epoxy resin	29690-82-2	7.39%	0.0813	73,909
				phenol resin	9003-35-4	7.39%	0.0813	73,909
				carbon black	1333-86-4	0.18%	0.002	1,818
				metal hydroxide	1309-42-8	2.0%	0.022	20,000
plating	matte tin	1.18%	0.013	Sn	7440-31-5	1.18%	0.013	11,818

*EMC GREEN molding compound is Halogen-Free.